



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN IPG-DIS/14/8337
Dated 19 Feb 2014

Power Rectifiers

Additional Assembly and Test Location in China for DPAK package

Table 1. Change Implementation Schedule

Forecasted implementation date for change	12-Feb-2014
Forecasted availability date of samples for customer	12-Feb-2014
Forecasted date for STMicroelectronics change Qualification Plan results availability	12-Feb-2014
Estimated date of changed product first shipment	21-May-2014

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	Selected Power Rectifiers in DPAK package
Type of change	Assembly additional location
Reason for change	to increase ST's manufacturing capacity
Description of the change	see attached
Change Product Identification	marking, internal codification and QA number
Manufacturing Location(s)	

DOCUMENT APPROVAL

Name	Function
Paris, Eric	Marketing Manager
Duclos, Franck	Product Manager
Cazaubon, Guy	Q.A. Manager

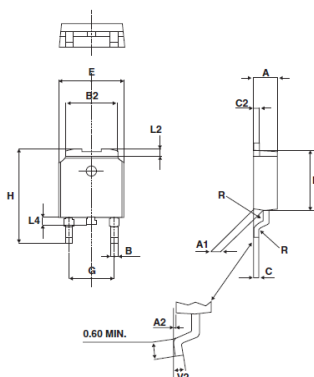
PCN

Product/Process Change Notification

Power Rectifiers			
Additional Assembly and Test Location in China for DPAK package			
Notification number:	IPG-DIS/14/8337	Issue Date	12/02/2014
Issued by	Aline AUGIS		
Product series affected by the change		<u>Power Schottky Diodes</u> STPS15H100CB-TR STPS5H100B-TR <u>Ultrafast Diodes</u> STTH5R06B-TR STTH506B-TR STTH1003SB-TR	
Type of change		Additional assembly package location	

Description of the change

STMicroelectronics decided to **expand the manufacturing capacity Power Rectifiers** (Power Schottky and Ultrafast Diodes) housed in **DPAK package** with one **additional assembly** and **test plant** in China.
In order to cover both manufacturing locations DPAK package outline dimensions, the package dimension table of the impacted products will be updated as below:



Original DPAK dimensions specified in datasheets			NEW DPAK dimensions specified in datasheets		
	Dimensions (mm)			Dimensions (mm)	
	Min.	Max.		Min.	Max.
A	2.2	2.4	A	2.18	2.4
A1	0.9	1.1	A1	0.9	1.1
A2	0.03	0.23	A2	0.03	0.23
B	0.64	0.9	B	0.64	0.9
B2	5.2	5.4	B2	4.95	5.46
C	0.45	0.6	C	0.45	0.61
C2	0.48	0.6	C2	0.46	0.6
D	6	6.2	D	5.97	6.22
E	6.4	6.6	E	6.35	6.73
G	4.4	4.6	G	4.4	4.7
H	9.35	10.1	H	9.35	10.34
L2	0.80 typ.		L2		1.27
L4	0.6	1	L4	0.6	1.02
V2	0°	8°	V2	0°	8°

Reason for change

This additional multi-sourcing will increase our **manufacturing capacity** for a better service on the considered **Power Rectifier** devices.

(1) IPG: Industrial & Power Group - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

Former versus changed product:	<p>The changed products do not present modified electrical, parameters, leaving unchanged the current information published in the product datasheet</p> <p>The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged.</p> <p>The footprint recommended by ST remains the same.</p> <p>There is no change in the packing modes and the standard delivery quantities either.</p>																				
Disposition of former products <p>As the purpose is to expand the manufacturing capacity, shipments of the products processed in the initial test and assembly site will continue.</p>																					
Marking and traceability <p>Parts produced in the new China location are differentiated by their marking as indicated below</p> <table><tr><th>Assembly location</th><th>Assy plant code</th><th colspan="2">Date code marking</th></tr><tr><td></td><td></td><th>Assy year</th><th>Assy week</th></tr><tr><td>China 1 (ST)</td><td>GK</td><td rowspan="2">Y (1 digit indicating the year)</td><td rowspan="2">WW (2 digits indicating the week number)</td></tr><tr><td>New location : China 2 (subco)</td><td>GE</td></tr></table>		Assembly location	Assy plant code	Date code marking				Assy year	Assy week	China 1 (ST)	GK	Y (1 digit indicating the year)	WW (2 digits indicating the week number)	New location : China 2 (subco)	GE						
Assembly location	Assy plant code	Date code marking																			
		Assy year	Assy week																		
China 1 (ST)	GK	Y (1 digit indicating the year)	WW (2 digits indicating the week number)																		
New location : China 2 (subco)	GE																				
Traceability for the implemented change will be ensured by an internal codification and by the Q.A. number .																					
Qualification complete date	27-Nov-2012																				
Forecasted sample availability <table><tr><th>Product family</th><th>Sub-family</th><th>Commercial part Number</th><th>Availability date</th></tr><tr><td>Diodes & Rectifiers</td><td>Power Schottky</td><td>STPS15H100CB-TR</td><td rowspan="5">Upon request with 4 weeks of delay</td></tr><tr><td>Diodes & Rectifiers</td><td>Power Schottky</td><td>STPS5H100B-TR</td></tr><tr><td>Diodes & Rectifiers</td><td>Ultrafast Diodes</td><td>STTH5R06B-TR</td></tr><tr><td>Diodes & Rectifiers</td><td>Ultrafast Diodes</td><td>STTH506B-TR</td></tr><tr><td>Diodes & Rectifiers</td><td>Ultrafast Diodes</td><td>STTH1003SB-TR</td></tr></table>		Product family	Sub-family	Commercial part Number	Availability date	Diodes & Rectifiers	Power Schottky	STPS15H100CB-TR	Upon request with 4 weeks of delay	Diodes & Rectifiers	Power Schottky	STPS5H100B-TR	Diodes & Rectifiers	Ultrafast Diodes	STTH5R06B-TR	Diodes & Rectifiers	Ultrafast Diodes	STTH506B-TR	Diodes & Rectifiers	Ultrafast Diodes	STTH1003SB-TR
Product family	Sub-family	Commercial part Number	Availability date																		
Diodes & Rectifiers	Power Schottky	STPS15H100CB-TR	Upon request with 4 weeks of delay																		
Diodes & Rectifiers	Power Schottky	STPS5H100B-TR																			
Diodes & Rectifiers	Ultrafast Diodes	STTH5R06B-TR																			
Diodes & Rectifiers	Ultrafast Diodes	STTH506B-TR																			
Diodes & Rectifiers	Ultrafast Diodes	STTH1003SB-TR																			

(1) IPG: Industrial & Power Group - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

Change implementation schedule

Sales types	Estimated production start	Estimated first shipments
All	Week 10 - 2014	Week 20 - 2014

Comments:

Customer's feedback

Please contact your local ST sales representative or quality contact for requests concerning this change notification.

Absence of acknowledgement of this PCN within 30 days of receipt will constitute acceptance of the change

Absence of additional response within 90 days of receipt of this PCN will constitute acceptance of the change

Qualification program and results

QRP11259QRP

Qualification of ECOPACK®2 resin for Rectifiers products in DPAK package

General Information	
Product Line	Rectifiers
Product Description	Rectifiers in DPAK package: ECOPACK®2 resin
Product Group	APM
Product division	ASD & IPAD
Package	DPAK
Maturity level step	Qualified

Locations	
Wafer fab	STM Tours (France) STM Singapore
Assembly plant	STM Long Gang (China) Subcontractor (China)
Reliability Lab	STM Tours (France)

DOCUMENT INFORMATION

Version	Date	Pages	Prepared by	Comment
1.0	21-Nov-2011	8	I. BALLON	First issue Qualification of Rectifiers products in DPAK package at STM Long Gang: ECOPACK®2 resin
2.0	03-Dec-2012	9		Qualification of DPAK package at subcontractor in China: ECOPACK®2 resin

Note: This report is a summary of the reliability trials performed in good faith by STMicroelectronics in order to evaluate the potential reliability risks during the product life using a set of defined test methods.

This report does not imply for STMicroelectronics expressly or implicitly any contractual obligations other than as set forth in STMicroelectronics general terms and conditions of Sale. This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.



TABLE OF CONTENTS

1	APPLICABLE AND REFERENCE DOCUMENTS.....	3
2	GLOSSARY	3
3	RELIABILITY EVALUATION OVERVIEW	3
3.1	OBJECTIVES.....	3
3.2	CONCLUSION	4
4	DEVICE CHARACTERISTICS	4
4.1	DEVICE DESCRIPTION	4
4.2	CONSTRUCTION NOTE	4
5	TESTS RESULTS SUMMARY	5
5.1	TEST VEHICLES	5
5.2	TEST PLAN AND RESULTS SUMMARY	5
6	ANNEXES.....	7
6.1	DEVICE DETAILS	7
6.2	PACKAGE OUTLINE/MECHANICAL DATA	8
6.3	TESTS DESCRIPTION.....	9

1 APPLICABLE AND REFERENCE DOCUMENTS

Document reference	Short description
JESD47	Stress-Test-Driven Qualification of Integrated Circuits
FMEA	8315678 - 8320100
RER	1126008 (ST Long Gang in China) – 1126011 (subcontractor in China)

2 GLOSSARY

DUT	Device Under Test
PCB	Printed Circuit Board
SS	Sample Size
HTRB	High Temperature Reverse Bias
TC	Temperature Cycling
PCT	Pressure Cooker Test (Pressure Pot)
THB	Temperature Humidity Bias
SD	Solderability

3 RELIABILITY EVALUATION OVERVIEW

3.1 Objectives

The objective of this report is to qualify “Halogen-Free” encapsulation molding compound for Rectifiers housed in DPAK package at ST Long Gang (China) and subcontractor in China.

The product series are listed below.

Product sub-Family	DPAK series
Power Schottky Diodes	STPSxxxB(-TR) STPSxxxCB(-TR) STPSxxHxxB(-TR) STPSxxHxxCB(-TR) STPSxxLxxB(-TR) STPSxxLxxCB(-TR)
Ultrafast Diodes	STTHxxxB(-TR) STTHxxxCB(-TR) STTHxxxSB(-TR) STTHxxLCDxxSB(-TR) STTHxxPxxSB(-TR) STTHxxRxxB(-TR) STTHxxSxxB(-TR)

The reliability methodology used in this qualification follows the JESD47-G: «Stress Test Driven Qualification Methodology».

3.2 Conclusion

The perimeter addressed in this campaign qualifies the production of Rectifiers housed in DPAK package at ST Long Gang (China) and subcontractor in China with the “Halogen-Free” encapsulation molding compound. Reliability tests are positive.

Qualification Plan requirements have been fulfilled without exception. Reliability tests have shown that the devices behave correctly against environmental tests (no failure). Moreover, the stability of electrical parameters during the accelerated tests demonstrates the robustness of the products and safe operation, which is consequently expected during their lifetime.

4 DEVICE CHARACTERISTICS

4.1 Device description

- Rectifiers in DPAK package with ECOPACK®2 Molding compound assembled at ST Long Gang (China) plant and subcontractor plant in China.

4.2 Construction note

Rectifiers in DPAK package with new ECOPACK®2 Molding compound	
Wafer/Die fab. information	
Wafer fab manufacturing location	STM Singapore STM Tours (France)
Wafer Testing (EWS) information	
Electrical testing manufacturing location	STM Singapore STM Tours (France)
Assembly information	
Assembly site	STM Long Gang (China) Subcontractor in China
Package description	DPAK
Molding compound	ECOPACK®2 (“Halogen-free”) molding compound
Frame material	Copper
Die attach process	Soft solder
Die attach material	Preform Pb/Sn/Ag
Wire bonding process	Ultra Sonic wire bonding
Wires bonding materials	Aluminium
Lead finishing process	Plating
Lead finishing material	Tin (Sn 100%)
Final testing information	
Testing location	STM Long Gang (China) Subcontractor in China

5 TESTS RESULTS SUMMARY

5.1 Test vehicles

Lot #	Process/ Package	Assembly plant	Product Family	Product
1	DPAK	ST China	Power Schottky	STPS15H100CB
2			Turboswitch	STTH512B
3			Power Schottky	STPS15H100CB
4			Turboswitch	STTH5R06B
5	D ² PAK		Power Schottky	STPS3045CG
6			Power Schottky	STPS30170CG
7			Ultrafast	STTH2004SG
8			Power Schottky	STPS41H100CG
9	DPAK		Turboswitch	STTH512B
10			Power Schottky	STPS15H100CB
11 / 15	DPAK	Subcontractor (China)	Power Schottky	STPS15L45CB
12 / 16				STPS15H100CB
13 / 17			Ultrafast	STTH512B
14 / 18				STTH5R06B

5.2 Test plan and results summary

Die Oriented Tests

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS				Note
						Lots 5 to 10	Lot 12	Lot 13	Lot 14	
HTRB	N	JESD22 A-108	T _j , V _r = 0.8xV _{rrm}	691	168 H	0/77	0/76	0/76	0/77	
					500 H	0/77	0/76	0/76	0/77	
					1000 H	0/77	0/76	0/76	0/77	

Package Oriented Tests

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS				Note
						Lot 1	Lot 2	Lot 11	Lot 13	
THB	Y	JESD22 A-101	T _a = 85°C, RH = 85%, V _r = 0.8xV _{rrm} or 100V max	198	168 H	0/25	0/77	0/24	0/24	
					500 H	0/25	0/77	0/24	0/24	
					1000 H	0/25	0/77	0/24	0/24	
TC	Y	JESD22 A-104	T _a = -55°C to 150°C	227	SS	Failure/SS				Note
					Steps	Lot 3	Lot 4	Lot 11	Lot 12	
					100 cy	0/25	0/25	0/25	0/25	0/25
					500 cy	0/25	0/25	0/25	0/25	0/25
					Steps	Failure/SS				
						Lot 15	Lot 16	Lot 17	Lot 18	
					100 cy	0/28	0/26	0/23	0/25	
					500 cy	0/28	0/26	0/23	0/25	




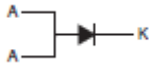
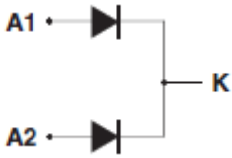
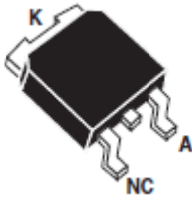
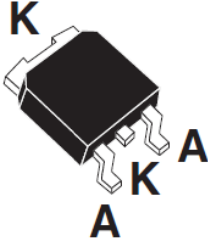
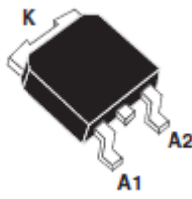
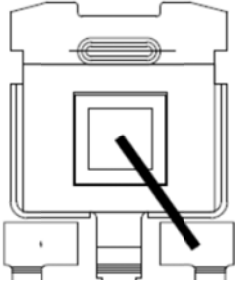
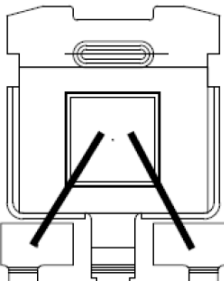
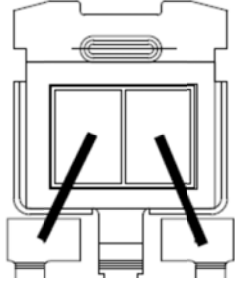
Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS					Note
						Lot 1	Lot 2	Lot 11	Lot 12	Lot 14	
PCT	Y	JESD22 A-102	121°C, 100% RH, 2bars	276	96hrs	0/24	0/77	0/25	0/25	0/25	
					Steps	Failure/SS					
						Lot 15	Lot 16	Lot 17	Lot 18		
					96hrs	0/25	0/25	0/25	0/25		

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS					Note
						Lot 1	Lot 2	Lot 11	Lot 12	Lot 14	
Solderability	N	J-STD-002	245°C SnAgCu bath Dry aging	50		0/10	0/10	0/10	0/10	0/10	
			245°C SnAgCu bath Wet aging	50		0/10	0/10	0/10	0/10	0/10	
				SS	Steps	Failure/SS					Note
						Lot 1	Lot 2	Lot 11	Lot 12	Lot 14	
			220°C SnPb bath Dry aging	50		0/10	0/10	0/10	0/10	0/10	
			220°C SnPb bath Wet aging	50		0/10	0/10	0/10	0/10	0/10	

6 ANNEXES

6.1 Device details

6.1.1 Pin connection and bonding diagram

Package	Pin connection		
	For Single diode configuration STPSxxxxB STTHxxxxB	For Single diode configuration STPSxxxxSB STTHxxxxSB	For Double diodes configuration STPSxxxxCB STTHxxxxCB
DPAK			
			
			

6.2 Package outline/Mechanical data

DPAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.18	2.39	0.085	0.94
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.89	0.025	0.035
B2	4.95	5.46	0.194	0.214
C	0.46	0.61	0.018	0.024
C2	0.46	0.60	0.018	0.023
D	5.97	6.22	0.235	0.244
D1	5.0		0.196	
E	6.35	6.73	0.25	0.264
E1	4.32		0.170	
e1	4.40	4.7	0.173	0.185
H	9.35	10.34	0.368	0.407
L	1.0	1.78	0.039	0.070
L2		1.27		0.05
L4		1.01		0.039

6.3 Tests description

Test name	Description	Purpose
Die Oriented		
HTRB High Temperature Reverse Bias HTFB / HTGB High Temperature Forward (Gate) Bias	The device is stressed in static configuration, trying to satisfy as much as possible the following conditions: low power dissipation; max. supply voltage compatible with diffusion process and internal circuitry limitations;	To determine the effects of bias conditions and temperature on solid state devices over time. It simulates the devices' operating condition in an accelerated way. To maximize the electrical field across either reverse-biased junctions or dielectric layers, in order to investigate the failure modes linked to mobile contamination, oxide ageing, layout sensitivity to surface effects.
Package Oriented		
TC Temperature Cycling	The device is submitted to cycled temperature excursions, between a hot and a cold chamber in air atmosphere.	To investigate failure modes related to the thermo-mechanical stress induced by the different thermal expansion of the materials interacting in the die-package system. Typical failure modes are linked to metal displacement, dielectric cracking, molding compound delamination, wire-bonds failure, die-attach layer degradation.
THB Temperature Humidity Bias	The device is biased in static configuration minimizing its internal power dissipation, and stored at controlled conditions of ambient temperature and relative humidity.	To evaluate the package moisture resistance with electrical field applied, both electrolytic and galvanic corrosion are put in evidence.
AC/PCT Auto Clave (Pressure Pot)	The device is stored in saturated steam, at fixed and controlled conditions of pressure and temperature.	To investigate corrosion phenomena affecting die or package materials, related to chemical contamination and package hermeticity.



Public Products List

PCN Title : Power Rectifiers // Additional Assembly and Test Location in China for DPAK package

PCN Reference : IPG-DIS/14/8337

PCN Created on : 13-FEB-2014

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

STPS15H100CB-TR
STTH506B-TR

STPS5H100B-TR
STTH5R06B-TR

STTH1003SB-TR

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

RESTRICTIONS OF USE AND CONFIDENTIALITY OBLIGATIONS:

THIS DOCUMENT AND ITS ANNEXES CONTAIN ST PROPRIETARY AND CONFIDENTIAL INFORMATION. THE DISCLOSURE, DISTRIBUTION, PUBLICATION OF WHATSOEVER NATURE OR USE FOR ANY OTHER PURPOSE THAN PROVIDED IN THIS DOCUMENT OF ANY INFORMATION CONTAINED IN THIS DOCUMENT AND ITS ANNEXES IS SUBMITTED TO ST PRIOR EXPRESS AUTHORIZATION. ANY UNAUTHORIZED REVIEW, USE, DISCLOSURE OR DISTRIBUTION OF SUCH INFORMATION IS EXPRESSLY PROHIBITED.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners

© 2014 STMicroelectronics - All rights reserved.

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com